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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# 3M™ Anisotropic Conductive Film 5363

## Product Description

3M™ Anisotropic Conductive Film (ACF) 5363 is a heat-bondable, electrically conductive adhesive film. The unbonded film is non-tacky at room temperature and consists of a thermoset-thermoplastic adhesive matrix randomly loaded with conductive particles. These particles allow inter-connection of circuit lines through the adhesive thickness, but are spaced far enough apart for the product to be electrically insulating in the plane of the adhesive. Application of heat and pressure causes the adhesive to flow and to bring the circuit pads into contact by trapping the conductive particles. The adhesive rapidly cures at modest bonding temperature. The 3M ACF 5363 may be used to bond a flexible printed circuit to another flexible printed circuit or to a printed circuit board.

## Construction

### General Properties

Property	Value
Adhesive Type	Thermosetting Type
Particle Type	Gold-Coated Nickel
Particle Size	10 micron
Liner Type	Polyester Film with Silicone Release
Adhesive Thickness	40 micron
Liner Thickness	50 micron

## Typical Physical Properties and Performance Characteristics

**Note:** The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

### Design Requirements

Property	Value	Units
Minimum Space Between Conductors	100 (4)	micron (mil)
Minimum Pitch	200 (8)	micron (mil)
Minimum Pad Area	0.15 (240)	sq. mm (sq. mil)

### Ambient Physical Properties

Property <sup>(1)</sup>	Test Substrates	Value	Test Method
Interconnect Resistance	Flex-to-PC board <sup>(2)</sup>	< 20 mOhms	3M TM-2314 <sup>(3)</sup>
Peel Strength <sup>(4)</sup>	Flex-to-PC board <sup>(2)</sup>	> 700 gf/cm	3M TM-2313 <sup>(5)</sup>

- (1) For a given application, values may differ depending on particular substrate material or type of circuitry.
- (2) Measured for gold/nickel/copper polyimide flex circuits bonded to printed circuit board. Contact overlap area was 0.15 sq. mm. Pad pitch was 200 microns.
- (3) 3M internal test method TM-2314 based on test method IPC 650 – Section 2.6.24. The flex has the shorting strap located near the bond-line to approximate a 4-wire test structure and eliminate most extraneous resistance in the measurement due to the circuit lines.
- (4) Results listed for minimum bonding conditions of 160°C x 5 sec. Higher values are possible with increase in bonding temperature or time.
- (5) 3M internal test method TM-2313 based on test method IPC 650 – Section 2.4.9.1.





## Typical Physical Properties and Performance Characteristics (continued)

**Note:** The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

### Reliability Performance – Electrical Contact<sup>(6,7)</sup>

Test Conditions	Interconnect Resistance (mOhms) 3M TM-2314 <sup>(6)</sup>
85°C x 1000 hrs	< 100
125°C x 1000 hrs	< 100
-40°C x 1000 hrs	< 100
85°C / 85% RH x 1000 hrs	< 100
-40° to 85°C x 500 cycles	< 100
-40° to 100°C x 1000 cycles	< 100

### Reliability Performance – Peel Strength<sup>(6,7)</sup>

Test Conditions	Peel Strength (gf/cm) 3M TM-2313 <sup>(9)</sup>
100°C x 1000 hrs	> 700
-40°C to 100°C x 1000 cycles	> 700
85°C / 85% r. h. x 1000 hrs	> 700

## Assembly Process Techniques

### Assembly Process

A source of heat and pressure, such as a thermo-compression (hot bar) bonder is required for use of 3M™ Anisotropic Conductive Film 5363. Several commercially available models exist: a list of vendors can be obtained by calling the toll free number on the back of this Technical Data Sheet.

<sup>(6)</sup> For a given application, values may differ depending on particular flex circuit and PC board materials used.

<sup>(7)</sup> Measured for gold/nickel/copper polyimide flex circuits bonded to gold/nickel/copper/FR-4 PC board. Contact overlap area was 0.2 sq. mm. Pad pitch was 200 microns.

<sup>(8)</sup> 3M internal test method TM-2314 based on test method IPC 650 - Section 2.6.24. The flex has the shorting strap located near the bond-line to approximate a 4-wire test structure and eliminate most extraneous resistance in the measurement due to the circuit lines.

<sup>(9)</sup> 3M internal test method TM-2313 based on test method IPC 650 - Section 2.4.9.1.

## Tacking and Bonding Conditions

Procedure	Conditions
<b>Tacking Conditions</b>	
Temperature <sup>(10)</sup>	90 - 110°C
Pressure	1 - 15 kg/cm <sup>2</sup>
Time	~1 sec
<b>Bonding Conditions</b>	
Temperature <sup>(10)</sup>	195 - 210°C
Pressure	30 - 50 kg/cm <sup>2</sup>
Time <sup>(11)</sup>	10 - 20 sec

### Assembly Process (continued)

Bonding of 3M ACF 5363 requires a three-part procedure:

Tacking the film to one substrate (pre-tacking)

Removing the release liner

Bonding the first substrate to the second substrate.

A pre-tacking temperature of 90°C under a pressure of about 10 kg/cm<sup>2</sup> should be used. **For automated ACF application:** Set the ACF pretacking equipment to deliver the conditions provided in the Tacking and Bonding Conditions Table above. Slight adjustment to these conditions may be necessary for each application or for different types of circuitry. **For manual ACF application:** Cut the adhesive to the size of the flex circuit. Place the adhesive on the flex and set flex on hot plate at setpoint up to 90°C. Use roller to press adhesive onto the flex. After allowing flex and adhesive to cool, remove liner.

<sup>(10)</sup> Temperature measured in the adhesive. Thermode set points will be higher and will depend upon the substrate materials and bond equipment. A typical bonding set-up for a flex interconnect bond is a thermode temperature of 300°C and a bonding time of 10 seconds (see next note).

<sup>(11)</sup> The required minimum bonding temperature of 195°C is usually reached within the first 5 seconds of bonding. The adhesive should be bonded so that the temperature is held above the minimum of 195°C for at least an additional 5 seconds. Also, it may be desirable to hold pressure while cooling to below 100°C for maximum performance.

### Assembly Process Techniques (continued)

Final bonding must be done under heat and pressure, with a typical desirable bond line temperature at or above 200°C, held for 10 seconds, and a pressure of 30 kg/cm<sup>2</sup>. During bonding, electrical contact is typically achieved within the first seconds after the bond line reaches about 195°C. Additional time at temperature is necessary to fully cure the epoxy material to generate peel strength and the ultimate reliability. Bond times may vary depending upon the substrates to be bonded. For maximum mechanical and electrical performance, the pressure should be maintained while cooling to below 100°C. This increases the total bond time. The time required to drop adhesive bond-line temperature below 100°C is highly dependent upon the bonding equipment used.

### Storage

3M™ Anisotropic Conductive Film 5363 should be kept frozen in the original airtight shipping bag. 3M ACF 5363 has a shelf life of 15 months from date of manufacture when stored at temperature ≤ 2°C. The product should be allowed to warm to room temperature for approximately 30 minutes prior to use to prevent moisture condensation on the film. Whenever possible, 3M ACF 5363 should be kept away from high humidity environments as absorbed water can lead to moisture volatilization producing bubbles during heat bonding or gradual degradation of the product. The 3M ACF 5363 can be held at room temperature for product utilization provided the cumulative room temperature shelf life is not exceeded. The room temperature shelf life is 4 weeks.

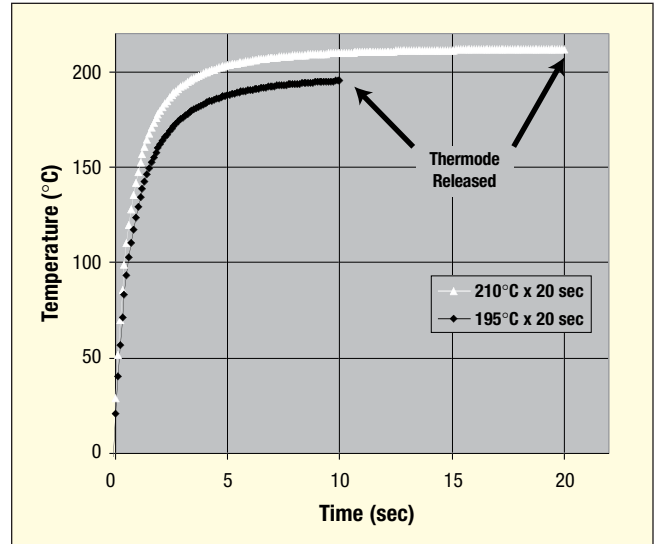


Figure 1. Graph of ACF temperature vs. time profile showing typical examples of bonding cycle.

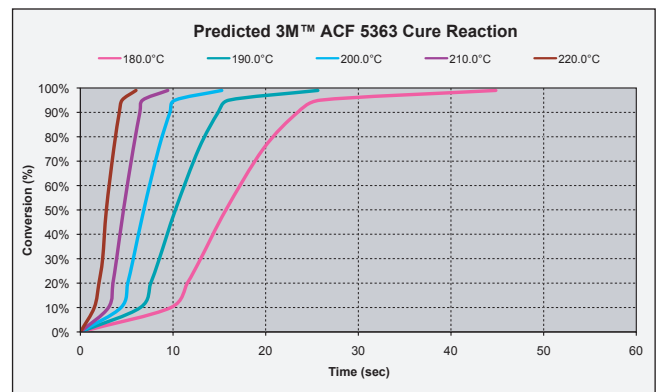


Figure 2. Graph of predicted cross-link reaction compared with bonding temperature and time.

### Shelf Life Data

Storage Environment	Value
Freezer (< 2°C)	15 months
Room Temperature	4 weeks

## Product Selection Guide

	Flex Type			Connection Type				Pitch and Space Requirements	
	Silver Ink on Polyester	Gold/Copper on Polyester	Gold/Copper on Polyimide	Flex to Glass	Flex to Plastic Device	Flex to PCB	Flex to Flex	Minimum Space Between Conductors	Minimum Pad Area
<b>ACF 5363</b>			X			X	X	100 micron	0.15 sq. mm
<b>ACF 7303</b>	X	X	X	X <sup>1</sup>	X <sup>2</sup>	X	X	250 micron	0.75 sq. mm
<b>ACF 7371</b>	X	X	X	X	X		X	100 micron	0.10 sq. mm
<b>ACF 7371-20</b>	X	X	X	X	X		X	100 micron	0.50 sq. mm
<b>ACF 7376-10</b>	X	X	X	X	X	X	X	70 micron	0.10 sq. mm
<b>ACF 7376-30</b>	X	X	X	X	X	X	X	100 micron	0.50 sq. mm
<b>ACF 7379</b>	X	X	X	X				50 micron	0.05 sq. mm

<sup>1</sup>Tested only for silver frit; not suitable for ITO traces.

<sup>2</sup>Suitable for silver ink traces only; not suitable for ITO traces.

## Technical Information

The technical information, recommendations and other statements contained in this document are based upon tests or experience that 3M believes are reliable, but the accuracy or completeness of such information is not guaranteed.

## Product Use

Many factors beyond 3M's control and uniquely within user's knowledge and control can affect the use and performance of a 3M product in a particular application. Given the variety of factors that can affect the use and performance of a 3M product, user is solely responsible for evaluating the 3M product and determining whether it is fit for a particular purpose and suitable for user's method of application.

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### Electronics Markets Materials Division

3M Center, Building 225-3S-06  
St. Paul, MN 55144-1000  
1-800-251-8634 phone  
651-778-4244 fax  
[www.3M.com/electronics](http://www.3M.com/electronics)

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60-5002-0130-0

